THE STUDY HOW TO ASSEMBLING SMD DEVICE INTEGRATED

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ABSTRACT

Nowadays, the size of electronic components is not macro anymore, but already in micro size, even nano. In designing electronic device using surface mount device (SMD), a number of special components which has better characteristics is oftentimes required because of the demand which can not be tolerated. Hermetic SMD (airproof SMD) is a preference to fulfill the demand for design of small size, light weight, perfect thermal performance, free of switching waves, and also higher circuit efficiency.

Keyword(s): assembling, SMD, thermal performance, effcient.

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